

NOVEL COMPOSITE FOIL, PROCESS FOR PRODUCING THE SAME
AND COPPER-CLAD LAMINATE

ABSTRACT

A composite foil comprising a conductive carrier, an organic release layer coating a surface of the conductive carrier, and a conductive particle layer
5 formed on the organic release layer. A process for producing a composite foil, comprising the steps of forming an organic release layer on a surface of a conductive carrier, and electrodepositing a conductive particle layer on the organic release layer. A copper-
10 clad laminate comprising the above composite foil laminated with a base material. A copper-clad laminate comprising the above composite foil laminated with a base material, having only the conductive carrier removed therefrom. Thus, there are provided a
15 composite foil for printed wiring board production from which a copper-clad laminate enabling laser perforating without forming burrs even at lower laser power and further enabling forming fine-pitch wiring patterns can be produced, a process for producing the composite foil
20 and a copper-clad laminate produced therefrom.

Figure 1